

-20V P-Channel Enhancement Mode MOSFET

DESCRIPTION

The SMC3401E is the P-Channel logic enhancement mode power field effect transistor is produced using high cell density, advanced trench technology to provide excellent $R_{DS(ON)}$.

This device is suitable for use as a load switch or in PWM and gate charge for most of the synchronous buck converter applications.

SMC3401ES-TRG ROHS Compliant This is Halogen Free

FEATURE

- ◆ -20V/-4.3A, $R_{DS(ON)} = 36m\Omega(typ)@V_{GS} = -10V$
- ◆ -20V/-3.5A, $R_{DS(ON)} = 43m\Omega(typ)@V_{GS} = -4.5V$
- ◆ -20V/-2.5A, $R_{DS(ON)} = 55m\Omega(typ)@V_{GS} = -2.5V$
- ◆ Super high density cell design for extremely low $R_{DS(ON)}$
- ◆ Exceptional on-resistance and maximum DC current capability

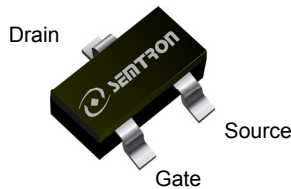
FEATURE

- ◆ DC/DC Converter
- ◆ Load Switch
- ◆ Mobile Battery Powered System

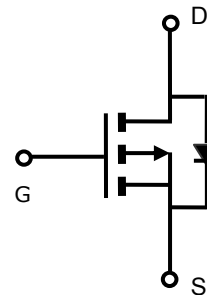


P-Channel Enhancement Mode MOSFET

PIN CONFIGURATION



SOT-23L
Top View



PART NUMBER INFORMATION

<p>SMC 3401E S - TR G</p> <p>a b c d e</p>	<p>a : Company name. b : Product Serial number. c : Package code d : Handling code e : Green produce code</p>
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ORDERING INFORMATION

Part Number	Package Code	Handling Code	Shipping
SMC3401ES-TRG	S : SOT-23L	TR : Tape&Reel	3K/Reel

- ※ Year Code : 0 ~ 9, 2010 : 0
- ※ Week Code : A(1~2) ~ Z(53~54)
- ※ SOT-23L : Only available in tape and reel packaging.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Typical	Unit	
V_{DSS}	Drain-Source Voltage	-20	V	
V_{GSS}	Gate-Source Voltage	± 12	V	
I_D	Continuous Drain Current ($T_C=25^\circ\text{C}$) ^A	$V_{GS}=-12\text{V}$	-4.3	A
	Continuous Drain Current ($T_C=70^\circ\text{C}$) ^A		-3.6	A
I_{DM}	Pulsed Drain Current ^B	-20	A	
P_D	Power Dissipation	$T_A=25^\circ\text{C}$	1.52	W
		$T_A=70^\circ\text{C}$	1.08	
T_J	Operation Junction Temperature	-55 to 150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.
 Absolute maximum ratings are stress ratings only and functional device operation is not implied.

THERMAL DATA

Symbol	Parameter	Typ	Max	Unit	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient ^A	Steady-State	-	120	$^\circ\text{C}/\text{W}$
$R_{\theta JL}$	Thermal Resistance Junction to Lead ^A	Steady-State	-	80	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS (T_J = 25°C Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-20			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.4	-0.65	-1.0	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±12V			±100	nA
I _{DSS}	Zero Gate Voltage, Drain-Source Leakage Current	V _{DS} =-20V, V _{GS} =0V T _J =25°C			-1	μA
		V _{DS} =-16V, V _{GS} =0V T _J =55°C			-5	
R _{DS(ON)}	Drain-source On-Resistance ^B	V _{GS} =-10V, I _D =-4.3A		36	40	mΩ
		V _{GS} =-4.5V, I _D =-3.5A		43	48	
		V _{GS} =-2.5V, I _D =-2.5A		55	65	
Source-Drain Diode						
V _{SD}	Diode Forward Voltage	I _S =-1.0A, V _{GS} =0V		-0.7	-1.0	V
I _S	Continuous Source Current ^{AD}				-1	A
Dynamic Parameters						
Q _g (-4.5V)	Total Gate Charge	V _{DS} =-15V V _{GS} =-10V I _D =-4.3A		9.8		nC
Q _{gs}	Gate-Source Charge			2.1		
Q _{gd}	Gate-Drain Charge			2.8		
C _{iss}	Input Capacitance	V _{DS} =-15V V _{GS} =0V f=1MHz		968		pF
C _{oss}	Output Capacitance			132		
C _{rss}	Reverse Transfer Capacitance			76		
t _{d(on)}	Turn-On Time	V _{DD} =-15V I _D =-4.3A		6.6		nS
t _r				3		
t _{d(off)}	Turn-Off Time	V _{GEN} =-10V R _G =6Ω		33		
t _f				13		

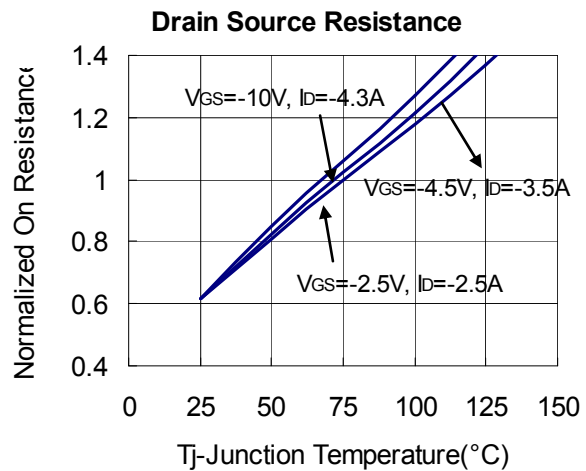
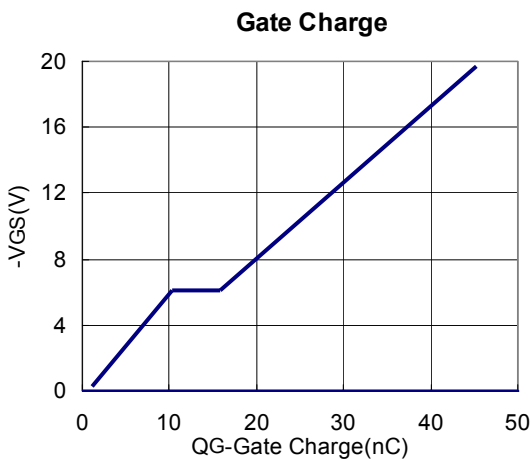
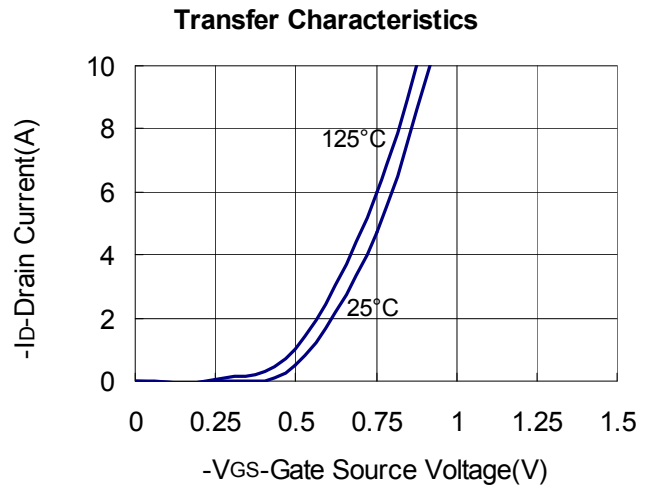
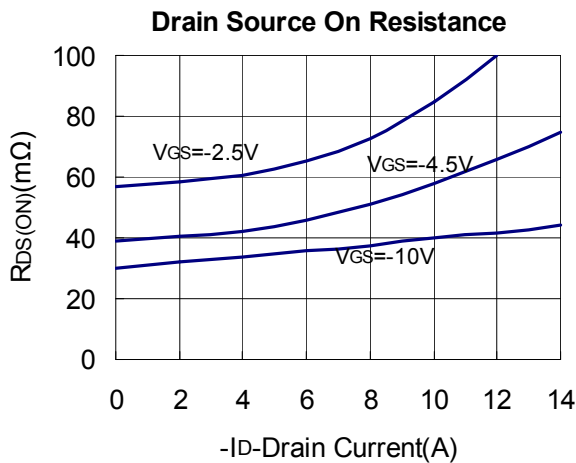
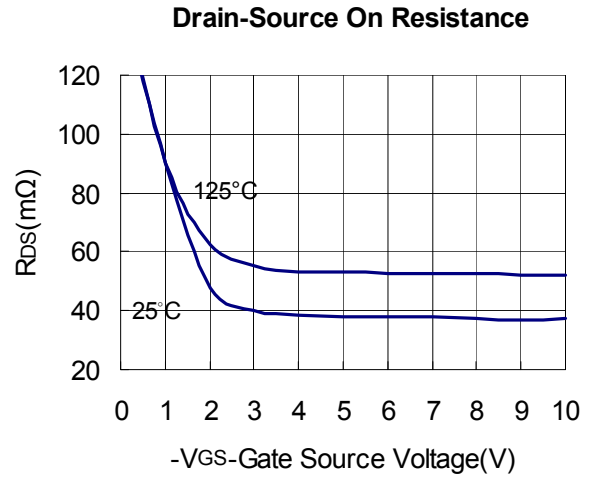
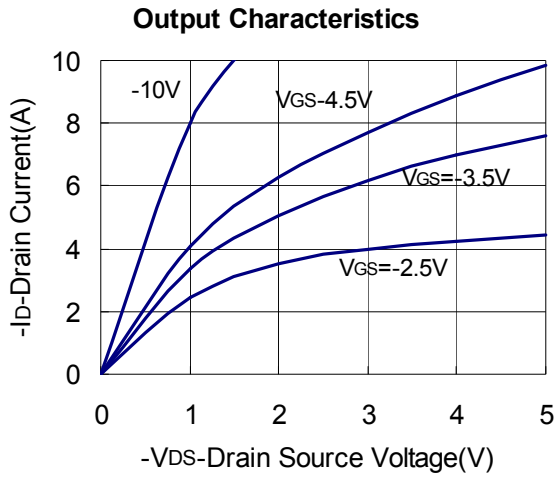
Note:

- The value of R_{θJA} is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.
- The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
- The EAS data shows Max. rating. The test condition is V_{DD}=-25V, V_{GS}=-10V, L=0.1mH.
- The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date

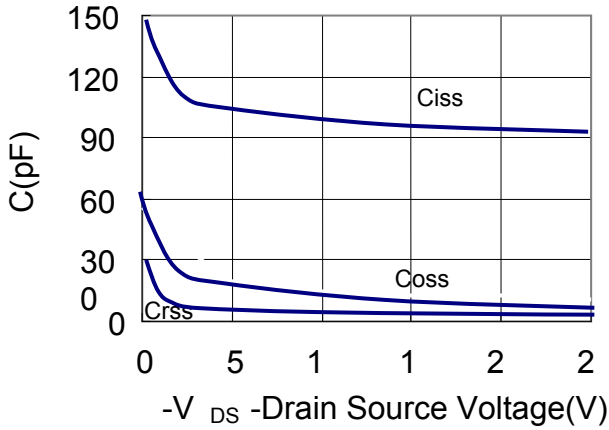
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TYPICAL CHARACTERISTICS (25°C Unless Note)

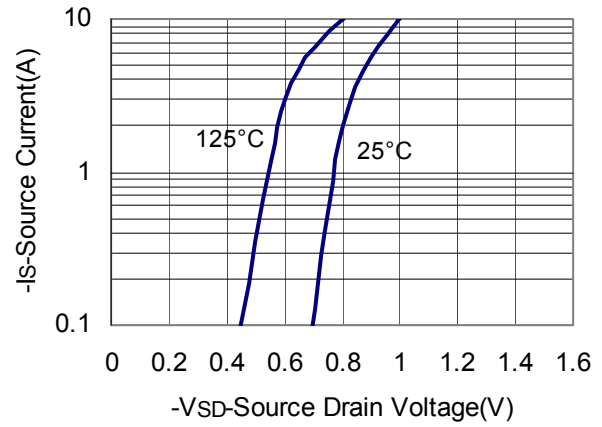


TYPICAL CHARACTERISTICS (25°C Unless Note)

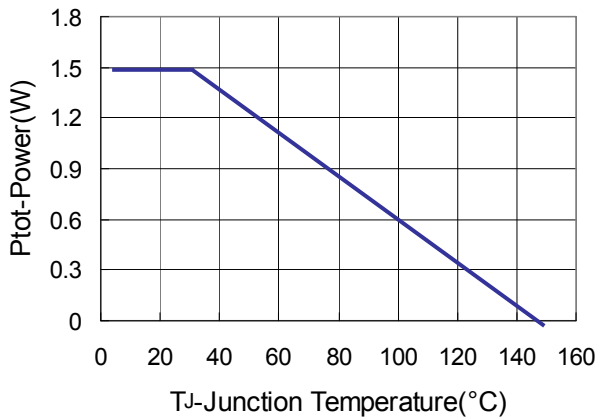
Capacitance



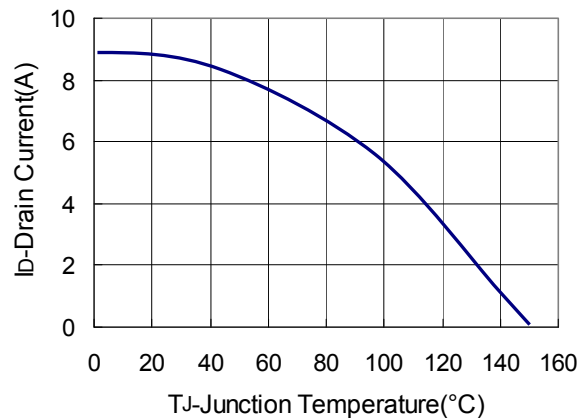
Source Drain Diode Forward



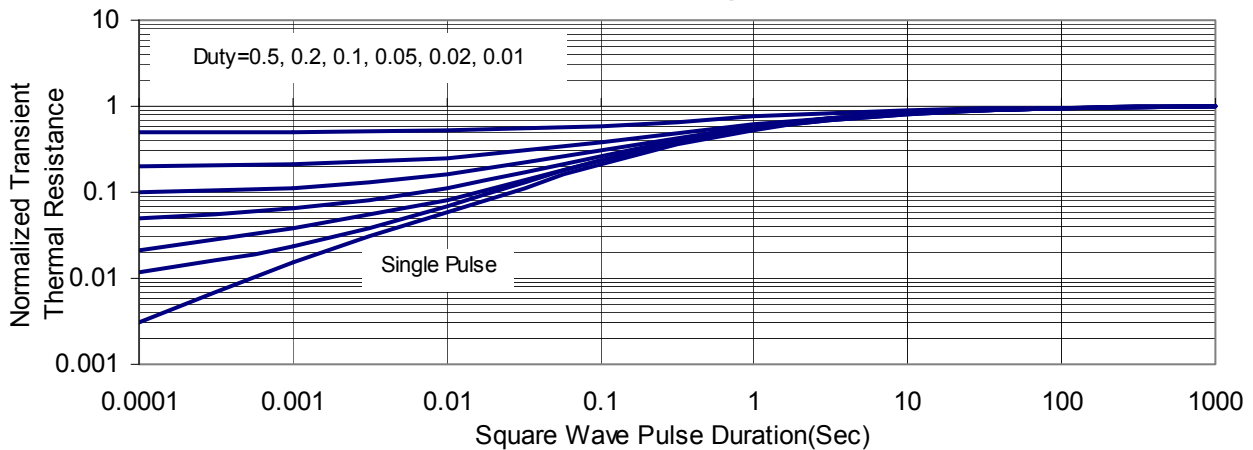
Power Dissipation



Drain Current



Thermal Transient Impedance



SOT-23L PACKAGE DIMENSIONS

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 BSC		0.037 BSC	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

SOT-23L PACKAGE OUTLINE DIMENSIONS

